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16. The method in claim 15, wherein said step of ensuring bond pad clearance further comprises rotating a chip around said axis at least to the extent that a bond pad on an underlying chip is exposed.

17. A method of arranging all dies in a multichip device, comprising:
serially stacking said all dies; and
establishing a unique orientation for each die of said all dies, wherein said orientation for said each die defines an underlying bond pad clearance.

REMARKS

Claims 7-17 are the only claims pending as of this Preliminary Amendment. In a restriction requirement issued in the parent application as part of the Office Action of April 9, 1999, the Examiner identified these claims (then numbered 21-31) as "Group II" claims "drawn to a method for making a multi chip device, classified in class 438, subclass 106+." Applicants assert that the pending claims address the novel and non-obvious aspects of the current invention. Accordingly, Applicants request allowance of these claims. If there are any matters that may be resolved or clarified through a telephone interview, the Examiner is requested to contact Applicants' undersigned attorney at the number indicated.

Respectfully submitted,

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